IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

Approved Meeting Minutes, prepared by John D'Ambrosia, Mark Nowell, Gary Nicholl, and Kent Lusted

9 March 2026
March 2026
Location: Vancouver, BC, Canada
IEEE P802.3dj Task Force Meeting Page - https://www.ieee802.org/3/dj/public/26_03/index.html

Session called to order at 1:21 p.m. Pacific Daylight Time (PDT) by John D'Ambrosia, Chair of the P802.3dj Task Force.

Chair reminded participants to declare their name and affiliation in the online meeting tool. Failure to declare would result in expulsion from the meeting.

Chair reminded participants that participation in the March 2026 meeting requires registration and payment of registration fee. The meeting will count towards IEEE 802.3 Working Group voting membership. (see Agenda slide #1)

If participants are not eligible to sign in to IMAT to claim attendance credit, please send an email to the Task Force Chair and Recording Secretary to be recorded in the minutes as an attendee.

Agenda:

Title	**Agenda and General Information**
Presenters	John D'Ambrosia
URL	https://www.ieee802.org/3/dj/public/26_03/agenda_3dj_b_2603.pdf

Chair welcomed everyone to the meeting.

Chair noted that every attendee at the IEEE 802.3 March 2026 meeting (Face-to-Face or Remote) must register and pay a fee to participate. (see slide #3 of agenda)

Chair reminded participants to sign into IMAT for Task Force attendance.

Chair reviewed the agenda (Slide #4). Chair noted that individuals should check the webpage for the latest version of each presentation. Chair noted that all of the presentation times were subject to change.

Chair asked if there were any objections to the agenda. There were none. The agenda was considered approved by unanimous consent.

Chair noted that the following meeting minutes needed to be approved (see slide #5)

- January 2026 Interim – https://www.ieee802.org/3/dj/public/26_01/minutes_3dj_a_2601_unapproved.pdf

Chair asked if there were any corrections or modifications to the posted minutes. No one responded. Chair asked if there were any objections to approving the minutes. There were none, and the minutes were considered approved by unanimous consent.

Chair reviewed the meeting map for the week. (See slides #6-9) He reviewed the details to find the track meetings' call information. He noted that straw polls may occur during any presentation, outside of noted "Discussion / Straw poll" agenda items. It was also noted that a breakout room has been assigned to the IEEE P802.3dj Task Force for offline consensus building during the meeting. If used, it will be announced and electronic meeting information will be provided via the Task Force reflector, and would be posted on the IEEE Call and Meeting calendar.

Chair reviewed meeting decorum. (See Slide #10-12) Chair asked if there were any members of the press present. No one responded.

Chair reviewed the goals for the session (see slide #13).

Chair reviewed the Task Force Project Information / Organization for the P802.3dj Task Forces. (See Slides #14-16).

Chair reviewed ground rules. (See Slide #17-18).

Chair reviewed voting in the task force. (see slide #19) Chair noted that the straw polls would use the online meeting tool. Motions would be taken with the Direct Vote Live tool if there was not unanimous consent. Chair noted that he reserved the right to take informative straw polls by 802.3 WG voting membership.

Chair reviewed the update membership and attendance recording requirements (see slide #20-21).
Chair noted that he would be reporting individuals signing into IMAT that did not meet the eligibility requirements.

Slide #22 - Chair noted that the information regarding the IEEE SA Policies had been sent out via the Task Force reflector , and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy and IEEE Code of Ethics

Chair asked if anyone needed to review the policies at that time – there were no requests to do so from in-person nor remote attendees.

Chair presented the third slide (See Slide #40) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #45) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair reminded participants of the IEEE Code of Ethics and Conduct. (See slide #48) He noted "All participants in IEEE-SA activities are expected to adhere to the core principles underlying the IEEE Code of Ethics and IEEE Code of Conduct".

Chair presented the second slide (See Slide #49) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair presented the third slide (See Slide #50) of the IEEE SA Participation Policy slides. Chair noted – "the standards development process shall not be dominated by any single interest category, individual, or organization"

Chair provided the details for the IEEE Ethics Reporting Line. (see Slide #52)

Chair reviewed the liaison responses and liaisons for consideration by the Task Force at the March 2026 meeting. (see Agenda slide #23) He noted that he would bring forward a liaison to the Working Group closing meeting.

Chair reminded participants that all contributions must be submitted with the PDF document properties properly completed. If the properties are not correct, the contribution would be returned.

Chair noted that he received a late presentation request from Mark Kimber on "TDECQ Limit and DFE Tap Weight Limit". He asked if there was objection to hearing the late presentation. No one responded.

Chair noted that he received a request from Ahmad El-Chayeb to withdraw his presentation. Ahmad noted there was an error in the data and would be brought forward in a future meeting.

Chair provided the participants with the access information to the Task Force private area.

Prior to the start of presentation #1, Adee Ran indicated that he had an updated version 04a with editorial corrections.

At 1:55 p.m. John D'Ambrosia passed the meeting chair responsibilities to Kent Lusted

Presentation #1:

Title	**Proposed Changes to Annex 180A and MDIs for DR Optics**
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/26_03/ran_3dj_04a_2603.pdf

Questions were asked and answered.

At 1:55 p.m. John D'Ambrosia resumed the meeting chair responsibilities.

Presentation #2:

Title	**Update MDIO register of local_tp_mode variable of CL 178B**
Presenters	Guangcan Mi
URL	https://www.ieee802.org/3/dj/public/26_03/mi_3dj_01a_2603.pdf

Questions were asked and answered.

Presentation #3:

Title	**Enabling coherent PMDs to participate in 802.3dj APSU**
Presenters	Marco Mascitto
URL	https://www.ieee802.org/3/dj/public/26_03/mascitto_3dj_01a_2603.pdf

Questions were asked and answered.

IMAT Reminder:

2:50 p.m. Chair reminded the room that this meeting required registration and payment of registration fee.

Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John

D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

PM Break

Break at 3:15 p.m. Resumed at 3:51 p.m.

Straw Poll #1:

Given that the LR1 and ER1 PHYs have different FEC, PMA below the FEC, and PMD sublayers, I would prefer having a common solution for communicating RTS across the LR1 and ER1 PHYs?
Results: Y: 20, N: 46

Straw Poll #2:

For the LR1 PHY, the APSU approach, outlined in mascitto_3dj_01a_2603, that I would prefer to adopt is:
A> Option A: PRBS31(Pages 6-7)
B> Option B: O2 Training Frame (Pages 8-9)
C> Option C: Pilot Sequences (Page 10)
(Chicago Rules)
Results: A: 39,   B: 18, C: 32

Straw Poll #3:

For the ER1 and ER1-20 PHYs, the APSU approach, outlined in mascitto_3dj_01a_2603, that I would prefer to adopt is:
A> Option A: PRBS31 (Pages 12-13)
B> Option B: O2 Training Frame (Pages 14-15)
C> Option C: ER1 Overhead (Pages 16-17)
(Chicago Rules)
Results: A: 21, B: 19,   C: 49

Straw Poll #4:

For the LR1 PHY, the APSU approach, outlined in mascitto_3dj_01a_2603, that I would prefer to adopt is:
A> PRBS31(Pages 6-7)
B> Pilot Sequences (Page 10)
(Choose one)
Results: A: 37,   B: 28

IMAT Reminder:

4:26 p.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #4:

Title	**Link failure and recovery with APSU**
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/26_03/ran_3dj_01a_2603.pdf

Questions were asked and answered.

Presentation #5:

Title	**APSU restart**
Presenters	Leon Bruckman
URL	https://www.ieee802.org/3/dj/public/26_03/bruckman_3dj_01_2603.pdf

Questions were asked and answered.

IMAT Reminder:

5:43 p.m. Chair reminded the room that this meeting required registration and payment of registration fee. Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D’Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Chair reminded participants to socialize their proposals and build consensus offline.

Meeting recessed for the day at 5:59 p.m.

10 March 2026
Session called to order at 8:05 a.m. PDT by John D'Ambrosia, Chair of the P802.3dj Task Force.

Chair reminded participants to declare their name and affiliation in the online meeting tool. Failure to declare would result in expulsion from the meeting.

Chair reminded participants that participation in the March 2026 meeting requires registration or payment of registration fee. The meeting will count towards IEEE 802.3 Working Group voting membership. (see Agenda slide #1)

If participants are not eligible to sign in to IMAT to claim attendance credit, please send an email to the Task Force Chair and Recording Secretary to be recorded in the minutes as an attendee.

Chair reminded that all participants in IEEE-SA activities are expected to adhere to the core principles underlying the:

- IEEE Code of Ethics
- IEEE Code of Conduct

Chair reminded participants to adhere to decorum. (see agenda slide #8)
Chair reminded participants that the use of AI tools in the meeting was not allowed.

Chair noted that the remaining presentation from Leon Bruckman would be heard either at the end of Wednesday or Thursday morning.

Presentation #6:

Title	**RxS Specification Proposal**
Presenters	Chris Cole
URL	https://www.ieee802.org/3/dj/public/26_03/cole_3dj_01_2603.pdf

Questions were asked and answered.

IMAT Reminder:
9:00 a.m. Chair reminded the room that this meeting required registration and payment of registration fee. Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Straw Poll #5:

I support the addition of a LRS (Low-stressed Receiver Sensitivity) test condition to the existing RxS specification.
Results: Y: 62 N: 12

Presentation #7:

Title	**OMAouter measurement with SSPRQ**
Presenters	Laurent Alloin
URL	https://www.ieee802.org/3/dj/public/26_03/alloin_3dj_01a_2603.pdf

Questions were asked and answered.

AM Break
Break at 9:50am Resumed at 10:30 a.m.

Presentation #8:

Title	**DFE normalization in TDECQ penalty computation**
Presenters	Laurent Alloin
URL	https://www.ieee802.org/3/dj/public/26_03/alloin_3dj_02a_2603.pdf

Questions were asked and answered.

IMAT Reminder:

11:15 a.m. Chair reminded the room that this meeting required registration and payment of registration fee. Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #9:

Title	**DFE differences between Annex 178A and Clause 180**
Presenters	Norm Swenson
URL	https://www.ieee802.org/3/dj/public/26_03/swenson_3dj_02_2603.pdf

Questions were asked and answered.

Lunch Break:

Break for lunch @ 12:00pm

Meeting reconvened @ 1:00pm

Presentation #10:

Title	**ITDECQ Limit and DFE Tap Weight Limit**
Presenters	Mark Kimber
URL	https://www.ieee802.org/3/dj/public/26_03/kimber_3dj_01a_2603.pdf

Questions were asked and answered.

Straw Poll #6:

I support the addition of the proposed clarification to the OMA_outer definition when measured using a SSPRQ as outlined in alloin_3dj_01a_2603 slide 13.

Results: Y:61 N:11

Straw Poll #7:

I support the proposed modifications to Table 180-16 regarding the DFE coefficient limit and associated footnote as outlined in alloin_3dj_02a_2603 slide 14.

Results: Y: 66 N: 12

Presentation #11:

Title	**TDECQ Considerations Revisited**
Presenters	Norm Swenson
URL	https://www.ieee802.org/3/dj/public/26_03/swenson_3dj_01a_2603.pdf

Questions were asked and answered.

IMAT Reminder:

2:30 p.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #12:

Title	**Refine the Rx Sensitivity/Tx OMA for DR/FR4-500/FR4**
Presenters	Michael He
URL	https://www.ieee802.org/3/dj/public/26_03/he_3dj_01_2603.pdf

Questions were asked and answered.

PM Break

Break at 3:15p.m. Resumed at 3:30 p.m.

Presentation #13:

Title	**Consideration on Tx/Rx OMAouter for FR4 and FR4-500**
Presenters	Xiaojie Fan
URL	https://www.ieee802.org/3/dj/public/26_03/fan_3dj_01a_2603.pdf

Questions were asked and answered.

Straw Poll #8:   DR/FR4-500

I support the direction to shift the optical Tx and Rx budget lower for the optical DR/FR4-500 optical specs as discussed in he_3dj_01_2603 and fan_3dj_01a_2603.
Result: Y: 44,   N: 28

Straw Poll #9:   FR4

I support the direction to shift the optical Tx and Rx budget lower for the optical FR4 optical specs as discussed in fan_3dj_01a_2603.
Result: Y: 31, N: 38

Presentation #14:

Title	**Transmitter Overshoot Penalty**
Presenters	Ali Ghiasi
URL	https://www.ieee802.org/3/dj/public/26_03/ghiasi_3dj_01a_2603.pdf

Questions were asked and answered.

IMAT Reminder:

4:35 p.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #15:

Title	**Capturing Jitter Penalty During TDECQ and FRx Tests**
Presenters	Ali Ghiasi
URL	https://www.ieee802.org/3/dj/public/26_03/ghiasi_3dj_02a_2603.pdf

Questions were asked and answered.

Recessed for the day at approximately 5:17p.m.

11 March 2026

Session called to order at 8:04 a.m. PDT by John D'Ambrosia, Chair of the P802.3dj Task Force.

Chair reminded participants to declare their name and affiliation in the online meeting tool. Failure to declare would result in expulsion from the meeting.

Chair reminded participants that participation in the March 2026 meeting requires registration or payment of registration fee. The meeting will count towards IEEE 802.3 Working Group voting membership. (see Agenda slide #1)

If participants are not eligible to sign in to IMAT to claim attendance credit, please send an email to the Task Force Chair and Recording Secretary to be recorded in the minutes as an attendee.

Chair reminded that all participants in IEEE-SA activities are expected to adhere to the core principles underlying the:

- IEEE Code of Ethics
- IEEE Code of Conduct

Chair reminded participants to adhere to decorum. (see agenda slide #8)

Chair noted that he would remove participants that join the zoom meeting without a declaration of affiliation or employer.

Chair noted that he received an updated contribution from Eric Maniloff with technical changes. He asked if there was objection to hearing the updated contribution. No one responded.

At 8:18 a.m. John D'Ambrosia passed the meeting chair responsibilities to Kent Lusted.

Presentation #16:

Title	**Consideration of Removal of Notes related to SFP224 and SFP-DD224 in Annex 179C**
Presenters	Sam Kocsis
URL	https://www.ieee802.org/3/dj/public/26_03/kocsis_3dj_01a_2603.pdf

Matt Brown, Howard Heck, Terry Little and Nathan Tracy asked to be listed as a supporter. Questions were asked and answered.

At 8:38 a.m, John D'Ambrosia resumed the meeting chair responsibilities.

Presentation #17:

Title	**MDI Connector Guidance**
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/26_03/ran_3dj_02a_2603.pdf

Questions were asked and answered.

Presentation #18:

Title	**Host, module, and test fixture illustrations for Annex 176D**
Presenters	Adee Ran
URL	https://www.ieee802.org/3/dj/public/26_03/ran_3dj_03a_2603.pdf

Norm Swenson, Mike Dudek, and Rick Rabinovich asked to be listed as a supporter. Questions were asked and answered.

IMAT Reminder:

9:13 a.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #19:

Title	**MTF ILdd revisited**
Presenters	Kent Lusted
URL	https://www.ieee802.org/3/dj/public/26_03/lusted_3dj_02a_2603.pdf

Questions were asked and answered.

Straw Poll #10

For the change to the Mated Test Fixture ILdd specification, I prefer the approach of:
A> no change needed
B> fitted ILdd mask
C> more details on de-embed/re-embed process included in the draft
D> B plus C
(choose one)

Results: A: 10   , B: 8   , C: 8 , D: 8

AM Break

Break at 10:05 a.m. Resumed at 10:38 a.m.

Presentation #20:

Title	**IEEE802.3dj Modal ERL Proposal**
Presenters	Rich Mellitz
URL	https://www.ieee802.org/3/dj/public/26_03/mellitz_3dj_01a_2603.pdf

Questions were asked and answered.

Straw Poll #11:

For Modal ERL, I would support the approach outlined in mellitz_3dj_01b_2603
Y: 31 , N: 8 , A: 22

IMAT Reminder:

11:32 a.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #21:

Title	**Consideration of BLER method using PMA measurements**
Presenters	Xuebo Wang
URL	https://www.ieee802.org/3/dj/public/26_03/wang_3dj_01a_2603.pdf

Matt Brown asked to be listed as a supporter. Questions were asked and answered.

Presentation #22:

Title	**176.10 Path data delay for time synchronization**
Presenters	Andras De Koos
URL	https://www.ieee802.org/3/dj/public/26_03/dekoos_3dj_01_2603.pdf

Questions were asked and answered.

Lunch Break

Break at 11:58 a.m. Resumed at 1:25 p.m.

Chair encouraged participants to discuss and build consensus on modal ERL over lunch. Chair outlined the plan to revisit the straw polls on the Modal ERL topic later in the day or the week.. An announcement would be sent over the email reflector. (see: https://www.ieee802.org/3/B400G/email/msg01797.html)

Presentation #23:

Title	**Clause 175 1.6TBASE-R hi_ser Timing and Codeword Count**
Presenters	Eric Maniloff
URL	https://www.ieee802.org/3/dj/public/26_03/maniloff_3dj_01_2603.pdf

Questions were asked and answered.

Straw Poll #12:

I would support specifying modal ERL (e.g. mellitz_3dj_01b_2603) for Clause 179 “CR”

Y: 22 , N: 15 , A: 20

IMAT Reminder:

2:30 p.m. Chair reminded the room that this meeting required registration and payment of registration fee.
Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D’Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #24:

Title	**Functional specs for AUI's reference PMD labeled registers labeled registers**
Presenters	Mike Dudek
URL	https://www.ieee802.org/3/dj/public/26_03/dudek_3dj_01_2603.pdf

Questions were asked and answered.

Presentation #25:

Title	**Figure 178B-9 optimization**
Presenters	Jeff Slavick
URL	https://www.ieee802.org/3/dj/public/26_03/slavick_3dj_03_2603.pdf

Questions were asked and answered.

PM Break

Break at 3:05 p.m. Resumed at 3:41 p.m.

Presentation #26:

Title	**rts_forward_timer duration concern**
Presenters	Jeff Slavick
URL	https://www.ieee802.org/3/dj/public/26_03/slavick_3dj_01_2603.pdf

Questions were asked and answered.

IMAT Reminder:

3:56 p.m. Chair reminded the room that this meeting required registration and payment of registration fee. Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #27:

Title	**APSU Data from end of LinkTrain to Link Up**
Presenters	Jeff Slavick
URL	https://www.ieee802.org/3/dj/public/26_03/slavick_3dj_02_2603.pdf

Questions were asked and answered.

Presentation #28:

Title	**Module receiver interference tolerance test revisited**
Presenters	Kent Lusted
URL	https://www.ieee802.org/3/dj/public/26_03/lusted_3dj_01_2603.pdf

Questions were asked and answered.

Chair noted that he received late presentation requests on Coherent ILT, Modal ERL, TFT and a deferred contribution from Leon Bruckman.

Chair reminded participants of the social event on Wednesday evening for in-person attendees.

Chair reminded participants of the 8:00 a.m. start time.

Chair thanked participants for their work on consensus building.

Chair thanked the Task Force for embracing the plan in January that lead to the progress at the March plenary.

Meeting recessed for the day at 4:31 p.m.

12 March 2026
Session called to order at 8:07 a.m. PDT by John D'Ambrosia , Chair of the P802.3dj Task Force. All time PDT unless stated otherwise.

Chair noted that every attendee at the IEEE 802.3 March 2026 meeting (Face-to-Face or Remote) must register and pay a fee to participate. (see slide #1 of agenda)

Chair reminded participants to declare their name and affiliation in the online meeting tool. Failure to declare would result in expulsion from the meeting.

All participants in IEEE-SA activities are expected to adhere to
the core principles underlying the:

- IEEE Code of Ethics
- IEEE Code of Conduct

Chair reminded participants to adhere to decorum. (see agenda slide #8)

Chair reviewed the plans for the day. He noted that there were late contributions from Tom Issenhuth, Rich Mellitz and Matt Brown. He noted that the contribution from Tom Issenhuth would be handled as a working item and would like to incorporate feedback during the review of the contribution.

Chair noted that the IEEE SA ballot was currently open and closes on 26 March. He reviewed the ways that participants could submit comments.

Presentation #29:

Title	**APSU Fail Action**
Presenters	Leon Bruckman
URL	https://www.ieee802.org/3/dj/public/26_03/bruckman_3dj_02a_2603.pdf

Questions were asked and answered.

At 8:30 a.m. John D'Ambrosia passed the meeting chair responsibilities to Mark Nowell.

Presentation #30:

Title	**Transmitter Functional Test Proposal**
Presenters	Tom Issenhuth
URL	No changes were made

The presenters asked individuals to provide written feedback for consideration by the author team. Questions were asked and answered.

At 9:31 a.m., John D'Ambrosia resumed the meeting chair responsibilities.

Presentation #31:

Title	**IEEE802.3dj Modal ERL Implementation**
Presenters	Rich Mellitz
URL	https://www.ieee802.org/3/dj/public/26_03/mellitz_3dj_03a_2603.pdf

Author noted an error for 179B.3.4 for fixtures and would provide an updated 03a. Slide 2 modal ERL mask. Add for CR. Questions were asked and answered.

AM Break
Break at 10:13 a.m. Resumed at 10:45 a.m.

Chair reminded participants that IMAT attendance credit for IEEE 802.3 Working Group attendance credit is not eligible in AM1 and AM2 on Thursday of the plenary weeks.

Straw Poll #13
I would support using modal ERL per mellitz_3dj_03a_2603 slides 2-3 for D3.1
Y: 45, N 13,   A 28

IMAT Reminder:
11:04 a.m. Chair asked that eligible participants should sign in to IMAT to claim Working Group attendance credit. He noted that participants not eligible to sign in to IMAT to claim Working Group attendance credit are to send an email to John D'Ambrosia / Kent Lusted to be recorded in the meeting minutes. He paused for a minute to let eligible attendees sign into IMAT. He asked if there was any eligible participant having a problem signing into IMAT. No one responded.

Presentation #32:

Title	**800GBASE-LR1 Coherent APSU Continued**
Presenters	Matt Brown
URL	https://www.ieee802.org/3/dj/public/26_03/brown_3dj_01a_2603.pdf

Questions were asked and answered.

Chair reviewed the future meetings. (See agenda slide #25.) He noted that the May interim meeting Tuesday would start on the next IMAT slot after the 400GPL Study Group ends, if the SG is formed.

Chair previewed the important dates for the May 2026 session. (see agenda slide #26). He noted that there would be two electronic meetings prior to the May interim meeting. He noted that the Task Force would meet on Friday, 15 May and that participants should make their travel arrangements accordingly.

Chair reviewed the future meetings and ad hocs.

Chair noted that the agenda was complete.

Meeting adjourned at 11:54 a.m.

Attendees (per IMAT)
Note: the Task Force attendance records below capture individuals that registered their attendance via IMAT for one or more "slots" on the specified day

Name	Employer	Affiliation
Abramczyk, Jaroslaw		Coherent
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Buckmeier, Brian	Belfuse INC	Bel Stewart Connector
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chan, Jason		Arista Networks
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
Chen, Lihao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Choudhury, Golam	Genuine Optics	Genuine Optics
Clay, Richard	Magnolia Electronics	Magnolia Electronics
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cox, Ian		Broadcom Corporation
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.

Name	Employer	Affiliation
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Elzur, Uri		NVIDIA Corporation
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
George, John	Lightera	Lightera
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics

Name	Employer	Affiliation
Hong, Paul	MaxLinear, Inc.	MaxLinear, Inc
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jin, Robert	Montage Technology, Inc	Montage Technology
Johnson, John	Broadcom Corporation	Broadcom Corporation
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO		Dexerials
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation

Name	Employer	Affiliation
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Mammenga, Kevin		Wilder Technologies
Maniloff, Eric	Ciena Corporation	Ciena Corporation

Name	Employer	Affiliation
Marques, Flavio	Lightera	Lightera
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Messica, Barak		NVIDIA
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
MURAKAMI, YUKI	1Finity	1Finity
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)

Name	Employer	Affiliation
Nikolich, Paul	Paul Nikolich	Paul Nikolich; Representing myself
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Phadke, Rohan	Arista Networks	Arista Networks
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated

Name	Employer	Affiliation
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Sekel, Steve	Wilder Technologies	wilder Technologoeis
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
She, Qingya	Fujitsu Network Communications	1FINITY
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Spruit, Hans	TRUMPF	Western Digital Corporation

Name	Employer	Affiliation
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
Theodoras, James	Scintil Photonics	Scintil Photonics
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks

Name	Employer	Affiliation
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co,. Ltd.
Yin, Shuang		Google
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
Zhu, Keyi		HUAWEI
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Name	Employer	Affiliation
Abraham, Shiju		Acsia Technologies
Abramczyk, Jaroslaw		Coherent
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Aripirala, Ravi		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Bar-Niv, Amir	Aquantia Corp	Marvell
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Buckmeier, Brian	Belfuse INC	Bel Stewart Connector
Budweiser, Karl		BMW AG; BMW Group
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chan, Jason		Arista Networks

Name	Employer	Affiliation
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
Chen, Lihao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
cheng, xiaoyue		Infineon Technologies
Chidambaram, Valliaappan		Acsia Technologies
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Genuine Optics	Genuine Optics
Clay, Richard	Magnolia Electronics	Magnolia Electronics
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cox, Ian		Broadcom Corporation
Dai, Shaoan		Infineon Technologies
Dalmia, Kamal	Aviva Links Inc	NXP Semiconductors
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.

Name	Employer	Affiliation
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
Edele, Jonas		BMW AG; BMW Group
Elangovan, Vivekanandh	Infineon Technologies	Infineon Technologies
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Enoki, Naomichi		Murata Electronics
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Fuller, Paul		Infineon Technologies
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gareau, Sebastien		Ciena Corporation
Gauthier, Claude	NXP Semiconductors	NXP Semiconductors
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
George, John	Lightera	Lightera
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Goel, Sachin	Aviva Links Inc	NXP

Name	Employer	Affiliation
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Graba, James	Broadcom Corporation	Broadcom Corporation
Gupta, Ajeya		General Motors Company
Hameed, Anil		Acsia Technologies
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hong, Paul	MaxLinear, Inc.	MaxLinear, Inc
Houck, TJ	Infineon Technologies	Infineon Technologies
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Hutchison, Guy	Aviva Links	Aviva Links Inc; Aviva Links Inc.

Name	Employer	Affiliation
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jin, Robert	Montage Technology, Inc	Montage Technology
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Joseph, Gloria		Acsia Technologies
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kandarpa, Venkata	Chelsio Communications	NXP Semiconductors
Kapoor, Samay	Aviva Links	Aviva Links Inc.
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO		Dexerials
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation

Name	Employer	Affiliation
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lee, Ching-Yen		Realtek Semiconductor Corp.
Lee, Dongjae		Newracom Inc.
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Lewis, Jon	Dell Technologies	Dell Technologies
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Hoei	NXP Semiconductors	NXP Semiconductors
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, YK		Realtek Semiconductor Corp.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
Lou, Wei		Broadcom Corporation
lu, chao	BMW Group	BMW Group
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Mammenga, Kevin		Wilder Technologies

Name	Employer	Affiliation
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	Lightera	Lightera
Martino, Kjersti	Inneos	Inneos
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Messica, Barak		NVIDIA
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael		Analog Devices Inc.
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
MURAKAMI, YUKI	1Finity	1Finity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nagaraja, Srikanth		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Ng, Hiok Tiaq	NXP Semiconductors	NXP Semiconductors
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)

Name	Employer	Affiliation
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Pal, Debajyoti		ON Semiconductor
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo		Broadcom Corporation
Pandey, Sujan	Velinktech	Velinktech
Parkholm, Ulf	Telefon AB LM Ericsson	Ericsson AB
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Phadke, Rohan	Arista Networks	Arista Networks
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Rajagopal, Karthik	Texas Instruments Inc.	Texas Instruments Inc.
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Infineon Technologies
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Name	Employer	Affiliation
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Schedl, Anton	BMW Group	BMW Group
Sedarat, Hossein	Ethernovia	Ethernovia
Sekel, Steve	Wilder Technologies	wilder Technologoeis
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
Sharma, Rohit		Molex Incorporated
She, Qingya	Fujitsu Network Communications	1FINITY
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Spruit, Hans	TRUMPF	Western Digital Corporation
Srivastava, Atul	NEL-America	NTT Electronics
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Sun, Yi	Lightera	Lightera

Name	Employer	Affiliation
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
TAKEUCHI, JUNICHI	JAE Electronics, Inc	JAE Electronics, Inc.
Tanc, Ahmet		NXP Semiconductors; NXP Semiconductors
Tanz, Simon		BMW AG; BMW Group
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics
Thomas, Rajan		Acsia Technologies
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Torres, Luisma	Knowledge Development for POF SL	KD
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Tu, Mike	Broadcom Corporation	Broadcom Corporation
Umar, Ashraf		Molex Incorporated
Urban, Luke		Magnolia Electronics
Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation
Vanderlaan, Paul	UL Solutions	Panduit Corp.
Veloso Cauce, Gumersindo	BMW Group	BMW AG; BMW Group
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Voss, Robert	Panduit Corp.	Panduit Corp.
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.

Name	Employer	Affiliation
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks
Wei, Terry		Analog Devices Inc.
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Wolfe, Jason	Bell Canada	Bell Canada
Wu, Dance	Marvell Semiconductor, Inc.	Infineon Technologies
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co,. Ltd.
Yin, Shuang		Google
Zerna, Conrad	Aviva Links Inc	NXP Semiconductors
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
Zhang, Wei		Broadcom Corporation
Zhu, Keyi		HUAWEI
ZHU, YUE		Huawei Technologies Co., Ltd
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Name	Employer	Affiliation
Abramczyk, Jaroslaw		Coherent
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Buckmeier, Brian	Belfuse INC	Bel Stewart Connector
Calvin, John	Keysight Technologies	Keysight Technologies
Chan, Jason		Arista Networks
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Lihao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Clay, Richard	Magnolia Electronics	Magnolia Electronics
Cox, Ian		Broadcom Corporation
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Dsilva, Hansel		Amphenol Corporation

Name	Employer	Affiliation
Dudek, Michael	Marvell	Marvell
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gareau, Sebastien		Ciena Corporation
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hong, Paul	MaxLinear, Inc.	MaxLinear, Inc
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jin, Robert	Montage Technology, Inc	Montage Technology
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.

Name	Employer	Affiliation
KATO, TAKAHIRTO		Dexerials
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Lessard, Stephane	Ericsson AB	Ericsson AB
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Mammenga, Kevin		Wilder Technologies
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mascitto, Marco	Infinera Canada Inc.	Nokia

Name	Employer	Affiliation
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
MURAKAMI, YUKI	1Finity	1Finity
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.

Name	Employer	Affiliation
Parkholm, Ulf	Telefon AB LM Ericsson	Ericsson AB
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Phadke, Rohan	Arista Networks	Arista Networks
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Sekel, Steve	Wilder Technologies	wilder Technologoeis
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
She, Qingya	Fujitsu Network Communications	1FINITY
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI

Name	Employer	Affiliation
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Srivastava, Atul	NEL-America	NTT Electronics
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
Theodoras, James	Scintil Photonics	Scintil Photonics
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Urban, Luke		Magnolia Electronics
Vanderlaan, Paul	UL Solutions	Panduit Corp.
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)

Name	Employer	Affiliation
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co,. Ltd.
Yin, Shuang		Google
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
Zhu, Keyi		HUAWEI
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Name	Employer	Affiliation
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Name	Employer	Affiliation
Abramczyk, Jaroslaw		Coherent
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Aripirala, Ravi		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chan, Jason		Arista Networks
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
cheng, xiaoyue		Infineon Technologies
Choudhury, Golam	Genuine Optics	Genuine Optics

Name	Employer	Affiliation
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cox, Ian		Broadcom Corporation
Dai, Shaoan		Infineon Technologies
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
Elangovan, Vivekanandh	Infineon Technologies	Infineon Technologies
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Enoki, Naomichi		Murata Electronics
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gareau, Sebastien		Ciena Corporation
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.

Name	Employer	Affiliation
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Graba, James	Broadcom Corporation	Broadcom Corporation
Hameed, Anil		Acsia Technologies
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hong, Paul	MaxLinear, Inc.	MaxLinear, Inc
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jeffreis, Brad		Analog Devices Inc.
Jin, Robert	Montage Technology, Inc	Montage Technology
Jochim, Markus	General Motors Company	General Motors Company

Name	Employer	Affiliation
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO		Dexerials
Kim, Do Kyun	LG ELECTRONICS	LG ELECTRONICS
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lee, Dongjae		Newracom Inc.
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.

Name	Employer	Affiliation
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
lu, chao	BMW Group	BMW Group
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Mammenga, Kevin		Wilder Technologies
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	Lightera	Lightera
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Messica, Barak		NVIDIA
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael		Analog Devices Inc.
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
MURAKAMI, YUKI	1Finity	1Finity
Murty, Ramana	Broadcom Inc.	Broadcom Corporation

Name	Employer	Affiliation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nagaraja, Srikanth		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Pal, Debajyoti		ON Semiconductor
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo		Broadcom Corporation
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation

Name	Employer	Affiliation
Peng, BC		MediaTek Inc.
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Phadke, Rohan	Arista Networks	Arista Networks
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Infineon Technologies
Reinhard, Michael	SEI Automotive Europe GmbH	SEI Automotive Europe GmbH
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Sekel, Steve	Wilder Technologies	wilder Technologoeis
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd

Name	Employer	Affiliation
She, Qingya	Fujitsu Network Communications	1FINITY
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
Spruit, Hans	TRUMPF	Western Digital Corporation
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics

Name	Employer	Affiliation
Thomas, Rajan		Acsia Technologies
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Urban, Luke		Magnolia Electronics
Veloso Cauce, Gumersindo	BMW Group	BMW AG; BMW Group
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Voss, Robert	Panduit Corp.	Panduit Corp.
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
wang, weilai	BMW Group	BMW AG; BMW Group
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks
Wei, Terry		Analog Devices Inc.
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation

Name	Employer	Affiliation
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co,. Ltd.
Yin, Shuang		Google
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
ZHU, YUE		Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd